

CTB Programme

Hybrids, MCM, Interconnection and Micropackaging WG

4th CTB – Hybrids - Agenda – 22 May 2007

- **9:30 - 9:45- Introduction** by Alberto Boetti - ESTEC TEC-QCT and Claude Drevon – Chairman CTB WG Hybrids
- **9:45 – 10:15 – Influence of PCB plating on reliability of CIN::APSE assemblies** - Claude Drevon – TAS – Toulouse - France
- **10:15 – 10:45 –Evaluation of soft soldering on Aluminium Nitride (AlN) substrates** – Damien Baudet – EADS Astrium – Velizy - France
- **10:45 – 11:15 - PCMC (Pure Copper Metallized Ceramic) package for high power applications** – Sebastian Libon – TAS ETCA – Charleroi – Belgium
- **11:15 – 11:45 – Glob-Top of RF chips investigations during FaFr developments** - Claude Drevon – TAS – Toulouse - France
- **Lunch**
- **13:30 – 14:00 - RF MEMS switches realized using LTCC (Low Temperature Ceramic Cofiring) Technology** – Sergio Di Nardo – TAS – L'Aquila - Italy
- **14:00 – 14:30 – 3D MoP (3 Dimensional Microwave Packaging)** – Geert Carchon – IMEC – Leuven - Belgium
- **14:30 – 15:00 – Testing of the assembly of a ceramic 625 MCGA packages on PCB (preliminary results)** - Stanley Mattsson – SAAB Gotemborg – Sweden
- **15:00 – 15:30 – Dye penetrant Test for High Pin Count BGA assemblies, report and procedure** – Luca Sollecchia – TAS – L'Aquila - Italy
- **15:30 - 16:00 – Conclusions and General Discussion**